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SECTION 2. FORMS PTO/SB/08A and 08B (formerly Form PTO-1449)

TC 1700

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants:

Felton, et al.

Attorney Docket: 2550/117

Serial No:

10/002,953

Art Group Unit: 1734

Date Filed:

October 23, 2001

Examiner Name: Not Assigned

Invention:

MEMS Capping Method and Apparatus

LIST OF PATENTS AND PUBLICATIONS FOR APPLICANTS' INFORMATION DISCLOSURE STATEMENT

United States Patents

Examiner Initials	Reference Number	Document Number	Issue Date	Inventor	Class/Subclass
M M M M M M	AA AB AC AD AE AF	5,915,168 5,798,557 5,604,160 5,594,979 5,323,051 4,786,357	Jun. 22, 1999 Aug. 25, 1998 Feb. 18, 1997 Jan. 21, 1997 Jun. 21, 1994 Nov. 22, 1988	Salatino et al. Salatino et al. Warfield Borchelt et al. Adams et al. Campanelli et al.	438/110 257/416 437/209 29/25.35 257/417 156/633
Other Documents					
Examiner Initials	Reference Number	Author	Title of Article, Title of Item, Date, Page(s), Volume-Issue Number(s)		
<u>-sii</u>	AG	Smith et al.	Micromachined Packaging for Chemical Microsensors, IEEE Trans. Electron Devices, June 1988, Vol. 35, No. 6 (pp. 787-792,		
<u> 111 </u>	АН	Petersen et al.	numbered 192-197). Silicon Fusion Bonding for Pressure Sensors, Rec. of the IEEE Solid-State Sensor and Actuator Workshop, 1988, pp. 144-147, numbered 209-212.		
<u>M</u>	AI	Rudolf et al.	Silicon Microaccelerometer, Transducers'87, Rec. of the 4 th Int. Conf. on Solid-State Sensors and Actuators, 1987, pp. 395-398, numbered 376-379.		

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Ko et al. Bonding Techniques for Microsensors, Micromachining and Micropackaging of Transducers, 1985, pp. 198-208. AK Roylance et al.

A Batch-Fabricated Silicon Accelerometer, IEEE Trans. Electron Devices, December 1979, Vol. ED-26, No. 12, pp. 1911-1917, numbered

352-358.

Examiner Signature: Months of Calbert

Date Considered:

NOTE FOR EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance AND not considered. Include copy of this form with next communication to applicant. (Page 5 of 7)